PCN Number:		20140306001						PCN Dat	te:	03/13/2014
Title:	Title:         Design Revision (NBTI Fix for Select TPS40077PWP Devices)									
Customer Contact:		PCN Manager Phon			e:	+1(214)480-	6037	Dept:	Quality Services	
Proposed 1 <sup>st</sup> Ship Da		te: 06/13/2014		014		Estim	Estimated			e provided at
		00/13/201		511	Avai		ilability:	san	nple request	
Change										
Assembly Site		Assembly Proc					Assembly Materials			
Design			Electrical Specificatio					Mechanical Specification Test Process		
Test Site Wafer Bump Site			Packing/Shipping/Lal Wafer Bump Material				$\square$	Wafer Bump Process		
Wafer Bump Site			Wafer Fab Materials				$\vdash$	Water Bump Process Wafer Fab Process		
			Part number change					Water Fub Frocess		
PCN Details										
Description of Change:										
change does not affect the device's guaranteed datasheet specifications or electrical performance. The affected devices are listed in the "Product Affected" section. The table below describes changes that were made:										
Description of Change Continuous improvement over time to negative bia (NBTI) under high tempe			nt to remove sensitivity ias temperature instability				Benefit of Change Improve reliability			
	for Change:									
Improve reliability										
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):										
None										
Changes to product identification resulting from this PCN:										
None										
Product Affected:										
TPS40077PWP TPS40077PWPG4					TPS40077PW	PS40077PWPR TPS40077PWPRG4				

Qualification Data: Approved 2/27/2014							
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.							
Qual Vehicle 1: TPS40077PWP							
Package/Die Construction Details							
Assembly Site: TAI		# Pins-Designator, Family:	P, HTSSOP				
Fab Process:	LBC4	Die Revision:	sion: C				
Qualification: 🗌 Plan 🛛 Test Results							
Reliability Test		Conditions	Sample Size (PASS/FAIL)				
High Temp Operating	Life	125C (168, 500, 1000 Hr	80/0				
Electrical Characteriza	ation, side by side	-	Pass				
ESD CDM		+/- 250V	3/0				
ESD HBM		+/- 1000V	3/0				
Latch-up		(per JESD78)	6/0				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com